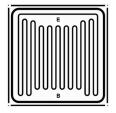


### **NPN Power Silicon Transistor Die**

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#### **Features**

- Available in commercial JANHCE and JANKCE MIL-PRF-19500/544
- Rad Tolerant to 100K rads (Si)
- Ideal for High Current Switching Applications



### Electrical Characteristics (T<sub>A</sub> = +25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Units	Min.	Max.
Collector - Emitter Breakdown Voltage	$I_{C}$ = 100 mA dc, $I_{B}$ = 0 $V_{(BR)}$		V dc	80	_
Emitter - Base Cutoff Current	$V_{EB} = 4.0 \text{ Vdc}, I_{C} = 0$ $V_{EB} = 5.5 \text{ Vdc}, I_{C} = 0$	I <sub>EBO1</sub> μΑ α		_	1.0 1.0
Collector - Emitter Cutoff Current	$V_{CE} = 60 \text{ V dc}, V_{BE} = 0$ $V_{CE} = 100 \text{ V dc}, V_{BE} = 0$	I <sub>CES1</sub>		_	1.0 1.0
Collector - Emitter Cutoff Current	V <sub>CE</sub> = 40 Vdc, I <sub>B</sub> = 0	I <sub>CEO</sub>	μA dc	_	50
Forward Current Transfer Ratio	$I_C$ = 50 mA dc, $V_{CE}$ = 5.0 Vdc 2N5152, 2N5152L 2N5154, 2N5154L $I_C$ = 2.5 A dc, $V_{CE}$ = 5.0 Vdc 2N5152, 2N5152L 2N5154, 2N5154L $I_C$ = 5.0 Vdc	h <sub>FE1</sub>	-	20 50 30 70 20	90 200
	2N5152, 2N5152L 2N5154, 2N5154L	h <sub>FE3</sub>		40	
Collector - Emitter Saturation Voltage	$I_C$ = 2.5 Adc, $I_B$ = 250 mAdc $I_C$ = 5.0 Adc, $I_B$ = 500 mAdc	V <sub>CE(SAT)1</sub> V <sub>CE(SAT)2</sub>	V dc	_	0.75 1.50
Base - Emitter Voltage (nonsaturated)	$I_C = 2.5 \text{ A dc}, V_{CE} = 5.0 \text{ Vdc}$	V <sub>BE</sub>	V dc	_	1.45
Emitter - Base Saturation Voltage	$I_C$ = 2.5 A dc, $I_B$ = 250 mA dc $I_C$ = 5.0 A dc, $I_B$ = 500 mA dc	V <sub>BE(SAT)1</sub>	V dc	_	1.45 2.20
Collector-Emitter Cutoff Current	$T_{C}$ = +150°C $V_{CE}$ = 60 V dc, $V_{BE}$ = -2 V dc	I <sub>CEX</sub>	μA dc	_	25
Forward-Current Transfer Ratio	$T_C = -55^{\circ}C$ $V_{CE} = 5 \text{ V dc}, I_C = 2.5 \text{ A dc}$ $2N5152, 2N5152L$ $2N5154, 2N5154L$	h <sub>FE4</sub>		15 25	

(Continued next page)



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## Electrical Characteristics (T<sub>A</sub> = +25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Units	Min.	Max.	
Dynamic Characteristics						
Magnitude of Common Emitter Small-Signal Short-Circuit Forward Current Transfer Ratio	I <sub>C</sub> = 500 mA dc, V <sub>CE</sub> = 5.0 Vdc, f = 10 MHz 2N5152, 2N5152L 2N5154, 2N5154L		-	6 7	_	
Common-Emitter, Small-Signal, Short-Circuit, Forward-Current Transfer Ratio	I <sub>C</sub> = 100 mA dc, V <sub>CE</sub> = 5.0 Vdc, f = 1 kHz 2N5152, 2N5152L 2N5154, 2N5154L	h <sub>FE</sub>	-	20 50	_	
Open-Circuit Output Capacitance	V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1 MHz	C <sub>obo</sub>	pF	_	250	

## Absolute Maximum Ratings (T<sub>A</sub> = +25°C unless otherwise specified)

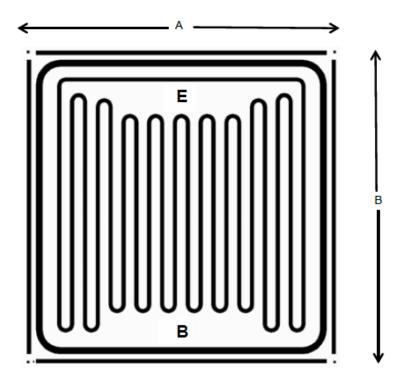
Ratings	Symbol	Value
Collector - Emitter Voltage	$V_{CEO}$	80 V dc
Collector - Base Voltage	$V_{CBO}$	100 V dc
Emitter - Base Voltage	V <sub>EBO</sub>	5.5 V dc
Collector Current	Ic	2 A dc 10 A dc <sup>(1)</sup>
Reverse Pulse Energy (2)		15 mJ



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#### **Outline Drawings (Die)**



Backside: COLLECTOR

Dimensions					
LTR	Inches		Millimeters		
	Min	Max	Min	Max	
Α	.118	.122	3.0	3.1	

#### NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- Unless otherwise specified, tolerance is ±.005 (0.13 mm).
- 4. The physical characteristics of the die are:

Thickness: .014 inch (0.35 mm) nominal, tolerance is ±.0015 (0.04 mm).

Top metal: Aluminum, 54,000 Å minimum, 60,000 Å nominal.

Back metal: Gold 6,400 Å minimum, 8,000 Å nominal.

Back side: Collector.

Bonding pad: B = .060 x .012 inch (1.5 mm x 0.30 mm)

 $E = .050 \times 0.12 \text{ inch } (1.27 \text{ mm} \times 0.30 \text{ mm})$ 

FIGURE 5. JANHC and JANKC (E-version) die dimensions.



**NPN Power Silicon Transistor Die** 

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